

# CGH55030F2 / CGH55030P2

## 25 W, C-band, Unmatched, GaN HEMT

Cree's CGH55030F2/CGH55030P2 is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH55030F2/CGH55030P2 ideal for C-band pulsed or CW saturated amplifiers. The transistor is available in both screw-down, flange and solder-down, pill packages. Based on appropriate external match adjustment, the CGH55030F2/CGH55030P2 is suitable for applications up to 6 GHz.



Package Type: 440196 & 440166  
PN: CGH55030P2 & CGH55030F2

### FEATURES

- 4.5 to 6.0 GHz Operation
- 12 dB Small Signal Gain at 5.65 GHz
- 30 W typical  $P_{SAT}$
- 60 % Efficiency at  $P_{SAT}$
- 28 V Operation

### APPLICATIONS

- 2-Way Private Radio
- Broadband Amplifiers
- Cellular Infrastructure
- Test Instrumentation
- Class A, AB Amplifiers for Drivers and Gain Blocks



Large Signal Models Available for SiC & GaN



## Absolute Maximum Ratings (not simultaneous) at 25 °C Case Temperature

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DSS}$	84	Volts
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts
Power Dissipation	$P_{DISS}$	28	Watts
Storage Temperature	$T_{STG}$	-55, +150	°C
Operating Junction Temperature	$T_J$	225	°C
Maximum Forward Gate Current	$I_{GMAX}$	7.0	mA
Soldering Temperature <sup>1</sup>	$T_S$	245	°C
Screw Torque	$\tau$	60	in-oz
Thermal Resistance, Junction to Case <sup>2</sup>	$R_{\theta JC}$	4.8	°C/W
Case Operating Temperature <sup>2,3</sup>	$T_C$	-40, +105	°C

Note:

<sup>1</sup> Refer to the Application Note on soldering at [www.cree.com/products/wireless\\_appnotes.asp](http://www.cree.com/products/wireless_appnotes.asp)

<sup>2</sup> Measured for the CGH55030 at  $P_{DISS} = 28$  W.

<sup>3</sup> See also, the Power Dissipation De-rating Curve on Page 4.

## Electrical Characteristics ( $T_C = 25^\circ\text{C}$ )

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.3	-2.3	VDC	$V_{DS} = 10$ V, $I_D = 7.2$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-3.0	-	VDC	$V_{DS} = 28$ V, $I_D = 250$ mA
Saturated Drain Current	$I_{DS}$	5.8	7.0	-	A	$V_{DS} = 6.0$ V, $V_{GS} = 2$ V
Drain-Source Breakdown Voltage	$V_{BR}$	84	100	-	VDC	$V_{GS} = -8$ V, $I_D = 7.2$ mA
<b>RF Characteristics<sup>2</sup> (<math>T_C = 25^\circ\text{C}</math>, <math>F_0 = 5.65</math> GHz unless otherwise noted)</b>						
Small Signal Gain	$G_{SS}$	9.0	11.0	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 250$ mA
Power Output <sup>3</sup>	$P_{SAT}$	20	30	-	W	$V_{DD} = 28$ V, $I_{DQ} = 250$ mA
Drain Efficiency <sup>4</sup>	$\eta$	50	60	-	%	$V_{DD} = 28$ V, $I_{DQ} = 250$ mA, $P_{SAT}$
Output Mismatch Stress	VSWR	-	10:1	-	$\Psi$	No damage at all phase angles, $V_{DD} = 28$ V, $I_{DQ} = 250$ mA, $P_{SAT}$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{GS}$	-	9.3	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Output Capacitance	$C_{DS}$	-	2.0	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Feedback Capacitance	$C_{GD}$	-	0.9	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz

Notes:

<sup>1</sup> Measured on wafer prior to packaging.

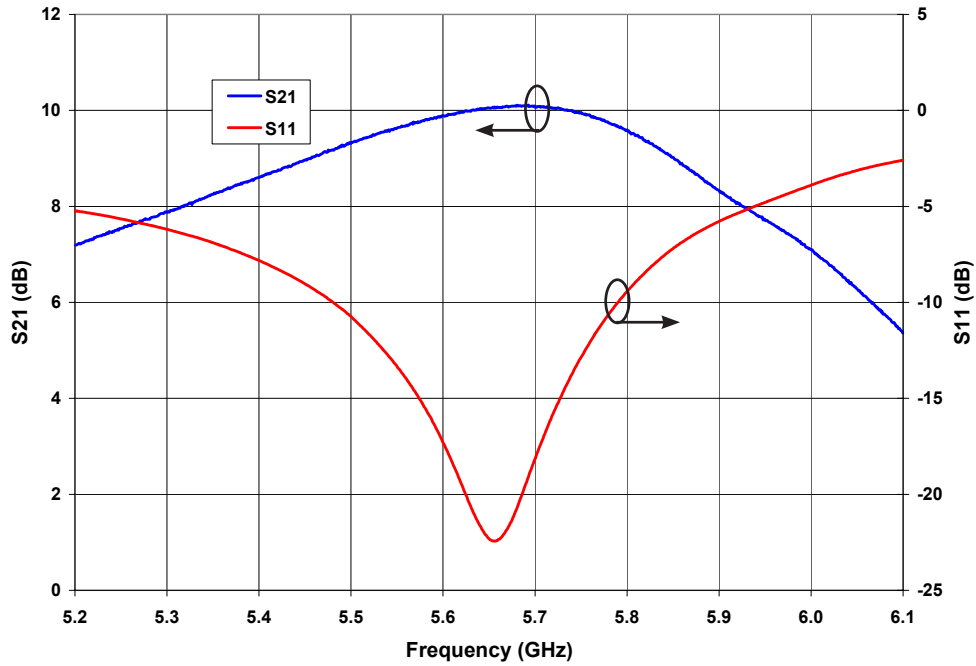
<sup>2</sup> Measured in CGH55030-TB.

<sup>3</sup>  $P_{SAT}$  is defined as  $I_G = 0.72$  mA.

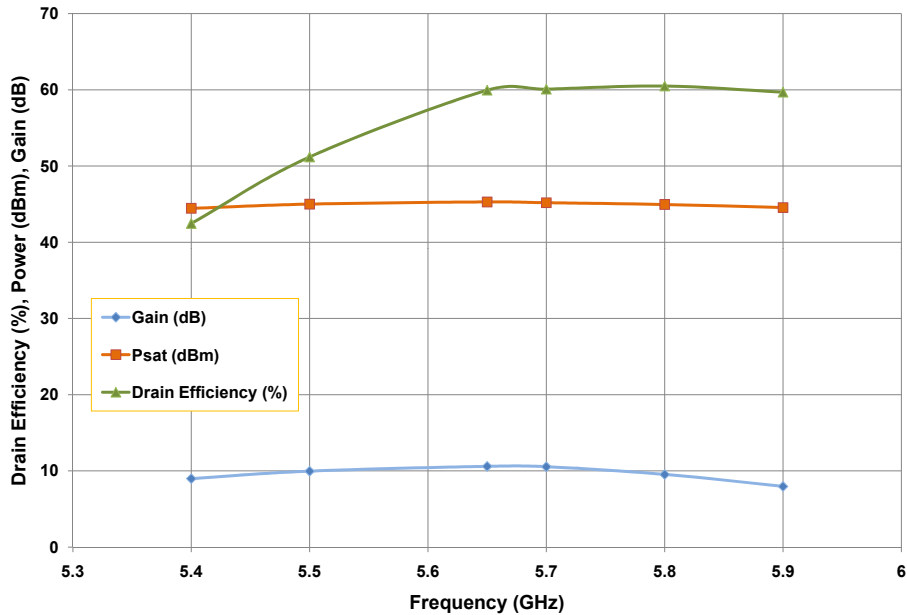
<sup>4</sup> Drain Efficiency =  $P_{OUT} / P_{DC}$

## Typical Performance

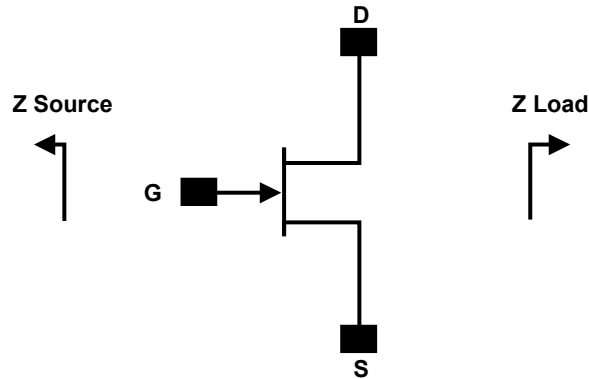
**Small Signal S-Parameters vs Frequency of  
CGH55030F2 and CGH55030P2 in the CGH55030-TB**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 250\text{ mA}$



**Drain Efficiency, Power and Gain vs Frequency of the  
CGH55030F2 and CGH55030P2 in the CGH55030-TB**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 250\text{ mA}$



## Source and Load Impedances

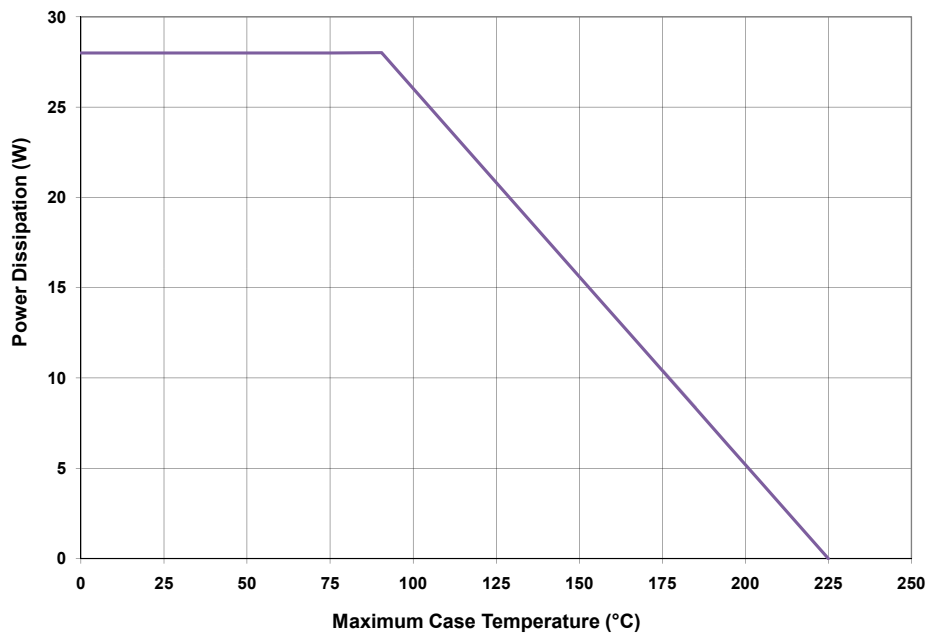


Frequency (MHz)	Z Source	Z Load
5500	8.0 - j12.4	14.1 - j12.6
5650	8.7 - j13.1	14.7 - j11.7
5800	8.4 - j14.0	15.4 - j11.0

Note 1.  $V_{DD} = 28V$ ,  $I_{DQ} = 250$  mA in the 440166 package.

Note 2. Impedances are extracted from the CGH55030-TB demonstration amplifier and are not source and load pull data derived from the transistor.

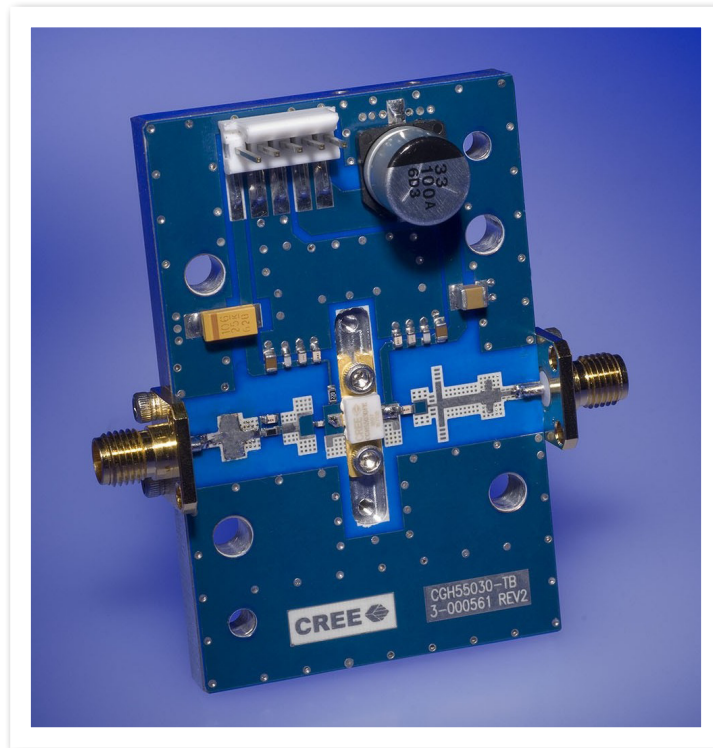
## CGH55030F2 and CGH55030P2 Power Dissipation De-rating Curve



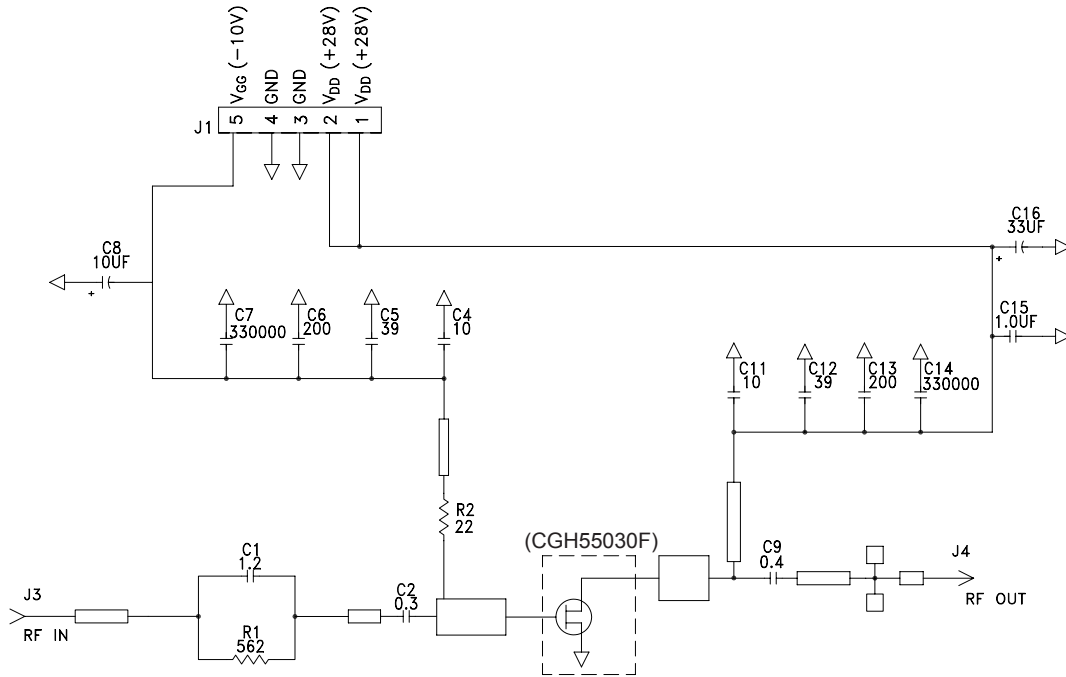
## CGH55030-TB Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 1/16W, 0603, 1%, 562 OHMS	1
R2	RES, 1/16W, 0603, 1%, 22.6 OHMS	1
C2	CAP, 0.3pF, +/-0.05pF, 0402, ATC600L	1
C16	CAP, 33 UF, 20%, G CASE	1
C15	CAP, 1.0UF, 100V, 10%, X7R, 1210	1
C8	CAP 10UF 16V TANTALUM	1
C9	CAP, 0.4pF, +/-0.05pF, 0603, ATC600S	1
C1	CAP, 1.2pF, +/-0.1pF, 0603, ATC600S	1
C6,C13	CAP,200 PF,0603 PKG, 100 V	2
C4,C11	CAP, 10.0pF,+/-5%, 0603, ATC600S	2
C5,C12	CAP, 39pF, +/-5%, 0603, ATC600S	2
C7,C14	CAP, 330000PF, 0805, 100V, TEMP STABILIZ	2
J3,J4	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
J1	HEADER RT>PLZ .1CEN LK 5POS	1
-	PCB, RO4350B, Er = 3.48, h = 20 mil	1
-	CGH55030	1

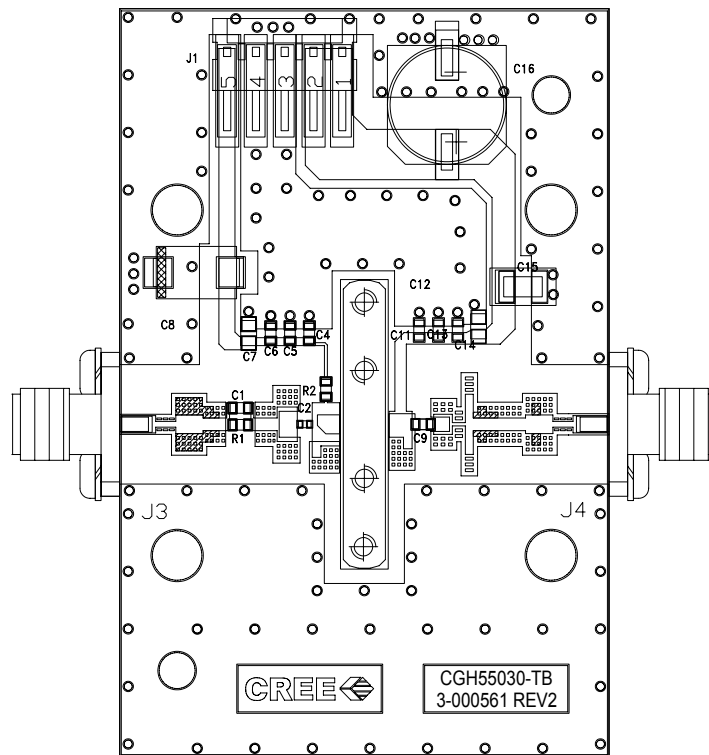
## CGH55030-TB Demonstration Amplifier Circuit



## CGH55030-TB Demonstration Amplifier Circuit Schematic



## CGH55030-TB Demonstration Amplifier Circuit Outline



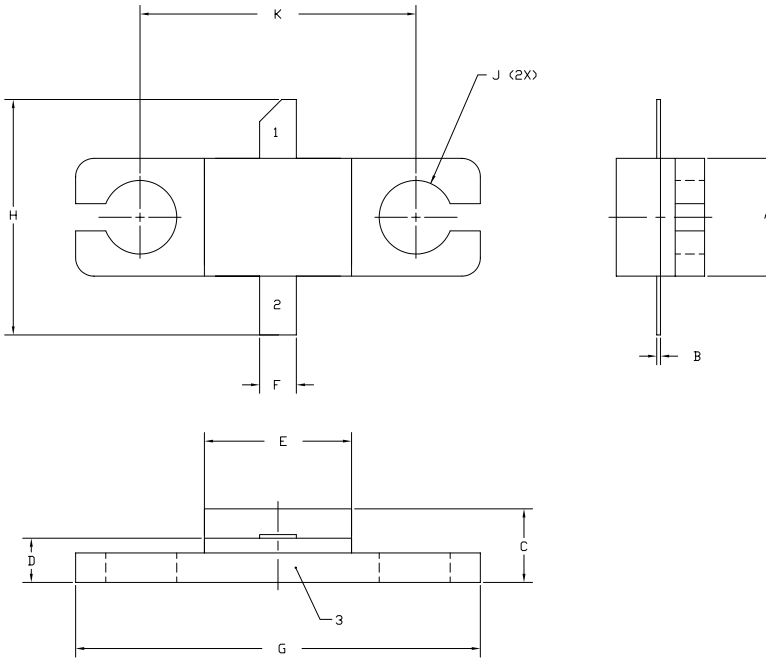


**Typical Package S-Parameters for CGH55030**  
**(Small Signal,  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 250\text{ mA}$ , angle in degrees)**

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.914	-163.42	12.17	89.92	0.021	5.48	0.528	-163.71
600 MHz	0.914	-167.32	10.17	86.47	0.021	3.15	0.531	-166.13
700 MHz	0.914	-170.31	8.73	83.46	0.021	1.28	0.534	-167.86
800 MHz	0.913	-172.73	7.65	80.72	0.021	-0.30	0.537	-169.14
900 MHz	0.913	-174.76	6.80	78.18	0.021	-1.68	0.540	-170.15
1.0 GHz	0.914	-176.53	6.11	75.78	0.021	-2.91	0.544	-170.97
1.1 GHz	0.914	-178.09	5.55	73.47	0.021	-4.03	0.547	-171.66
1.2 GHz	0.914	-179.52	5.08	71.24	0.021	-5.04	0.551	-172.26
1.3 GHz	0.914	179.17	4.69	69.08	0.020	-5.98	0.555	-172.80
1.4 GHz	0.915	177.95	4.35	66.96	0.020	-6.84	0.559	-173.30
1.5 GHz	0.915	176.79	4.05	64.89	0.020	-7.63	0.563	-173.77
1.6 GHz	0.915	175.68	3.79	62.86	0.020	-8.37	0.567	-174.23
1.7 GHz	0.916	174.62	3.56	60.85	0.020	-9.04	0.571	-174.68
1.8 GHz	0.916	173.60	3.36	58.88	0.020	-9.66	0.576	-175.13
1.9 GHz	0.916	172.60	3.18	56.93	0.019	-10.22	0.580	-175.59
2.0 GHz	0.917	171.62	3.01	55.00	0.019	-10.72	0.585	-176.05
2.1 GHz	0.917	170.67	2.86	53.09	0.019	-11.16	0.590	-176.52
2.2 GHz	0.918	169.72	2.73	51.21	0.019	-11.54	0.595	-177.01
2.3 GHz	0.918	168.79	2.60	49.34	0.019	-11.87	0.599	-177.51
2.4 GHz	0.919	167.87	2.49	47.49	0.018	-12.13	0.604	-178.03
2.5 GHz	0.919	166.95	2.39	45.66	0.018	-12.33	0.609	-178.56
2.6 GHz	0.919	166.04	2.29	43.84	0.018	-12.46	0.614	-179.11
2.7 GHz	0.920	165.13	2.20	42.03	0.018	-12.53	0.619	-179.68
2.8 GHz	0.920	164.22	2.12	40.24	0.017	-12.53	0.623	179.74
2.9 GHz	0.921	163.31	2.04	38.47	0.017	-12.46	0.628	179.13
3.0 GHz	0.921	162.41	1.97	36.70	0.017	-12.32	0.633	178.51
3.2 GHz	0.922	160.58	1.85	33.21	0.017	-11.83	0.642	177.22
3.4 GHz	0.923	158.73	1.73	29.76	0.016	-11.04	0.650	175.85
3.6 GHz	0.923	156.87	1.63	26.34	0.016	-9.97	0.659	174.42
3.8 GHz	0.924	154.97	1.55	22.96	0.016	-8.61	0.666	172.93
4.0 GHz	0.924	153.04	1.47	19.61	0.016	-7.01	0.674	171.37
4.2 GHz	0.925	151.06	1.40	16.29	0.016	-5.19	0.681	169.74
4.4 GHz	0.925	149.04	1.34	12.98	0.016	-3.21	0.688	168.06
4.6 GHz	0.925	146.97	1.28	9.68	0.016	-1.14	0.694	166.32
4.8 GHz	0.926	144.85	1.23	6.39	0.016	0.95	0.699	164.51
5.0 GHz	0.926	142.66	1.19	3.11	0.017	2.98	0.705	162.64
5.2 GHz	0.926	140.41	1.15	-0.18	0.018	4.88	0.709	160.70
5.4 GHz	0.926	138.08	1.11	-3.48	0.018	6.58	0.714	158.70
5.6 GHz	0.925	135.68	1.08	-6.79	0.019	8.03	0.717	156.63
5.8 GHz	0.925	133.19	1.05	-10.13	0.020	9.19	0.721	154.49
6.0 GHz	0.925	130.62	1.02	-13.50	0.022	10.03	0.724	152.27

Download this s-parameter file in ".s2p" format at [http://www.cree.com/products/wireless\\_s-parameters.asp](http://www.cree.com/products/wireless_s-parameters.asp)

## Product Dimensions CGH55030F (Package Type — 440166)



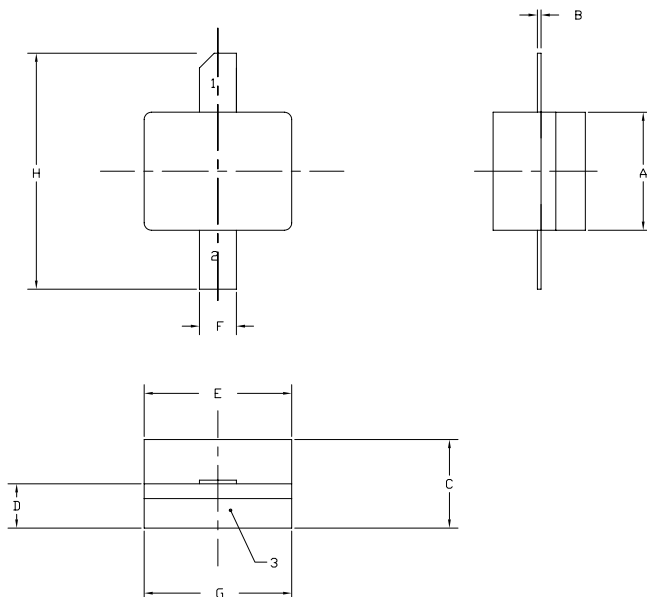
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE Ni/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.004	0.006	0.10	0.15
C	0.115	0.135	2.92	3.43
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.545	0.555	13.84	14.09
H	0.280	0.360	7.87	8.38
J	ø .100		2.54	
K	0.375		9.53	

- PIN 1. GATE  
PIN 2. DRAIN  
PIN 3. SOURCE

## Product Dimensions CGH55030P (Package Type — 440196)



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE Ni/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.003	0.006	0.10	0.15
C	0.115	0.135	2.92	3.17
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.195	0.205	4.95	5.21
H	0.280	0.360	7.112	9.114

- PIN 1. GATE  
PIN 2. DRAIN  
PIN 3. SOURCE





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